



STK11C68AM

CMOS/SNOS nvSRAM

Military

High Performance

8K x 8 Non-Volatile Static RAM

PRELIMINARY

FEATURES

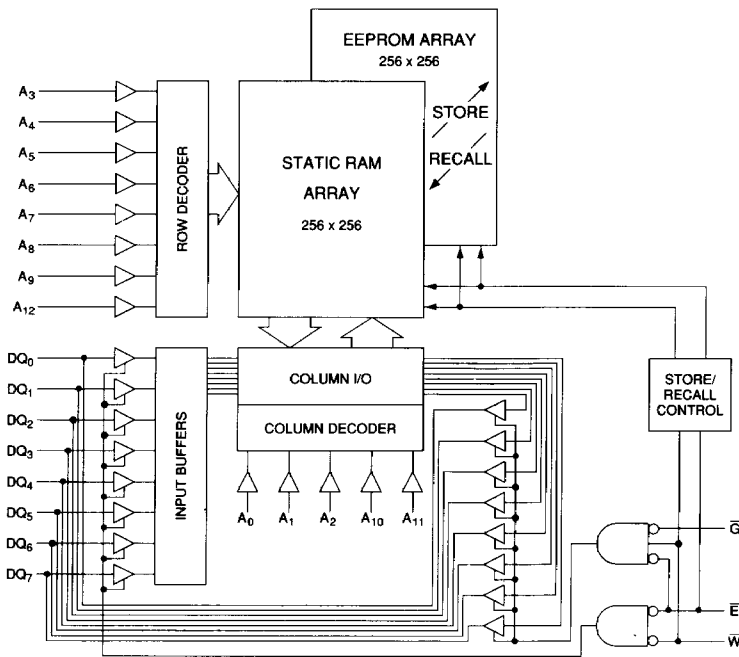
- Non-Volatile Data Integrity
- 45, 55 and 70ns Address Access Times
- 45, 55 and 70ns Chip Enable Access Times
- Unlimited Read and Write to SRAM
- Unlimited Recall cycles from EEPROM
- 10^5 Store cycles to EEPROM
- Software initiated Store to EEPROM
- Software initiated Recall from EEPROM
- Automatic Recall on Power Up
- Automatic Store Timing
- Single 5V $\pm 10\%$ Operation
- Military Temperature Range -55°C to 125°C
- 10 year data retention in EEPROM
- JEDEC SRAM pinout in a 600 mil 28 pin DIP
- JEDEC SRAM pinout in a 32 pin LCC
- Available in an industry standard 300 mil DIP

DESCRIPTION

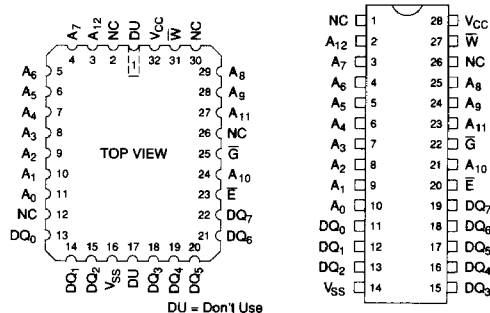
The Simtek STK11C68AM is a fast static RAM (35, 45 and 55ns), with a non-volatile electrically-erasable PROM (EEPROM) cell incorporated in each static memory cell. The SRAM can be read and written an unlimited number of times, while independent non-volatile data resides in EEPROM. Data transfers from the SRAM to the EEPROM (STORE) or from the EEPROM to the SRAM (RECALL) are initiated through software sequences. A RECALL also takes place upon power-up. It combines the high performance and ease of use of a fast SRAM with the data integrity of non-volatility.

The STK11C68AM features the JEDEC standard pinout for 8K x 8 SRAMs in a 28-pin 600 mil dual in line package, a 32 pin LCC or a 28-pin 300 mil DIP. will be screened to MIL-STD method 5004 and 5005. Simtek is currently establishing a military standard compliant program.

LOGIC BLOCK DIAGRAM



PIN CONFIGURATIONS



PIN NAMES

| | |
|-----------------------------------|----------------|
| A ₀ - A ₁₂ | Address Inputs |
| W | Write Enable |
| DQ ₀ - DQ ₇ | Data In/Out |
| E | Chip Enable |
| G | Output Enable |
| V _{CC} | Power (+5V) |
| V _{SS} | Ground |



ABSOLUTE MAXIMUM RATINGS^a

Voltage on typical input relative to V_{SS}-0.6V to 7.0V
 Voltage on DQ_{0-7} and \bar{W}-0.5V to $(V_{CC}+0.5V)$
 Temperature under bias.....-55°C to 125°C
 Storage temperature.....-65°C to 150°C
 Power dissipation.....1W
 DC output current.....15mA
 (One output at a time, one second duration)

Note a: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC OPERATING CONDITIONS

| SYMBOL | PARAMETER | MIN | TYP | MAX | UNITS | NOTES |
|----------|-------------------------------|--------------|-----|--------------|-------|------------|
| V_{CC} | Supply Voltage | 4.5 | 5.0 | 5.5 | V | |
| V_{IH} | Input Logic "1" Voltage | 2.0 | | $V_{CC}+0.5$ | V | All Inputs |
| V_{IL} | Input Logic "0" Voltage | $V_{SS}-0.5$ | | 0.8 | V | All Inputs |
| T_A | Ambient Operating Temperature | -55 | | 125 | °C | |

DC ELECTRICAL CHARACTERISTICS^{b,c}

(-55°C ≤ T_A ≤ 125°C) (V_{CC} = 5.0V ± 10%)

| SYMBOL | PARAMETER | MIN | MAX | UNITS | NOTES |
|-----------|---|-----|----------------|----------------|---|
| I_{CC} | Average V_{CC} Power Supply Current | | 90 85 80 | mA mA mA | $t_{AVAV}=45ns$ $t_{AVAV}=55ns$ $t_{AVAV}=70ns$ |
| I_{SB1} | V_{CC} Power Supply Current (Standby, Cycling TTL Input Levels) | | 19 19 19 | mA mA mA | $t_{AVAV}=45ns$ $t_{AVAV}=55ns$ $t_{AVAV}=70ns$ $E \geq V_{IH}$ all other inputs cycling |
| I_{SB2} | V_{CC} Power Supply Current (Standby, Stable CMOS Input Levels) | | 2 | mA | $E \geq (V_{CC}-0.2V)$ All other inputs at $V_{IN} \leq 0.2V$ or $\geq (V_{CC}-0.2V)$ |
| I_{ILK} | Input Leakage Current (Any Input) | | ± 1 | µA | $V_{CC} = max$ $V_{IN} = V_{SS}$ to V_{CC} |
| I_{OLK} | Off State Output Leakage Current | | ± 5 | µA | $V_{CC} = max$ $V_{IN} = V_{SS}$ to V_{CC} |
| V_{OH} | Output Logic "1" Voltage | 2.4 | | V | $I_{OUT} = -4mA$ |
| V_{OL} | Output Logic "0" Voltage | | 0.4 | V | $I_{OUT} = 8mA$ |

Note b: I_{CC} is dependent on output loading and cycle rate. The specified values are obtained with outputs unloaded.
 Note c: Bringing $E \geq V_{IH}$ will not produce standby currents levels until any non-volatile cycle in progress has timed out. See MODE SELECTION table.

AC TEST CONDITIONS

Input Pulse Levels V_{SS} to 3V
 Input Rise and Fall Times ≤ 5ns
 Input and Output Timing Reference Levels 1.5V
 Output Load See Figure 1

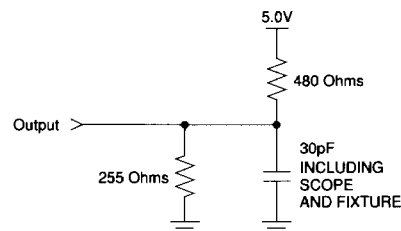


Figure 1: AC Output Loading

CAPACITANCE ($T_A=25^\circ C, f=1.0MHz$)^d

| SYMBOL | PARAMETER | MAX | UNITS | CONDITIONS |
|-----------|--------------------|-----|-------|--------------------|
| C_{IN} | Input Capacitance | 5 | pF | $\Delta V=0$ to 3V |
| C_{OUT} | Output Capacitance | 7 | pF | $\Delta V=0$ to 3V |

Note d: This parameter is characterized and not 100% tested.

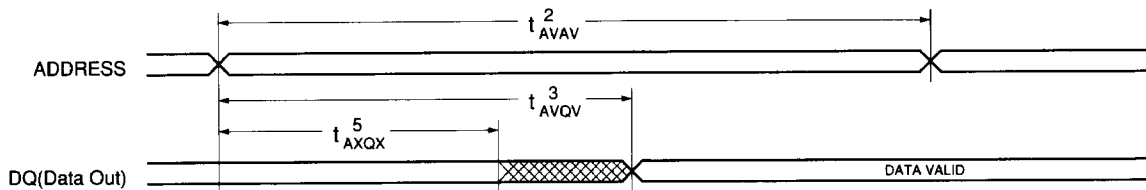
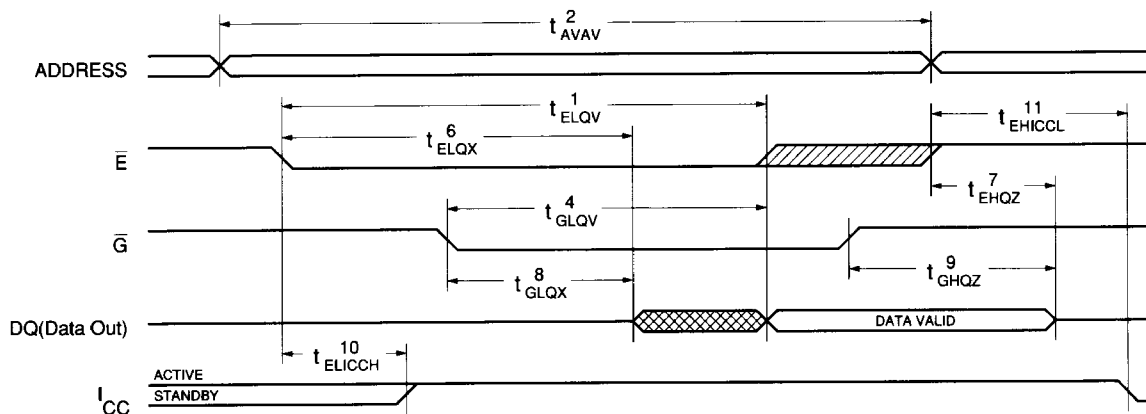
SRAM MEMORY OPERATION

READ CYCLES 1 & 2^e

 (-55°C ≤ T_A ≤ 125°C) (V_{CC} = 5.0V ± 10%)

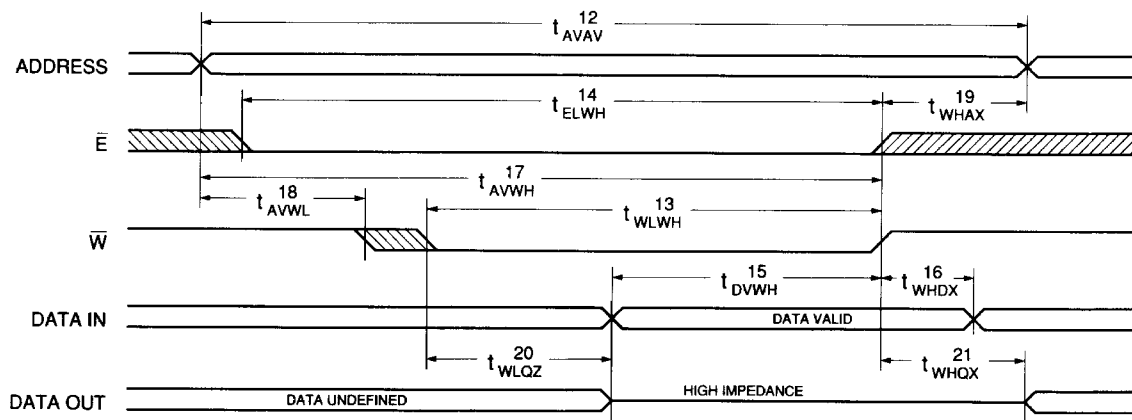
| NO. | SYMBOL | | PARAMETER | STK11C68AM-45 | | STK11C68AM-55 | | STK11C68AM-70 | | UNITS | NOTES |
|-----|---------------------|------------------|-----------------------------------|---------------|-----|---------------|-----|---------------|-----|-------|-------|
| | Standard | Alternate | | MIN | MAX | MIN | MAX | MIN | MAX | | |
| 1 | t _{ELOV} | t _{ACS} | Chip Enable Access Time | | 45 | | 55 | | 70 | ns | |
| 2 | t _{AVAV} | t _{RC} | Read Cycle Time | 45 | | 55 | | 70 | | ns | f |
| 3 | t _{AVQV} | t _{AA} | Address Access Time | | 45 | | 55 | | 70 | ns | g |
| 4 | t _{GLQV} | t _{OE} | Output Enable to Data Valid | | 20 | | 25 | | 30 | ns | |
| 5 | t _{AXQX} | t _{OH} | Output Hold After Address Change | 5 | | 5 | | 5 | | ns | |
| 6 | t _{ELQX} | t _{LZ} | Chip Enable to Output Active | 5 | | 5 | | 5 | | ns | |
| 7 | t _{EHQZ} | t _{OHZ} | Chip Disable to Output Inactive | | 20 | | 25 | | 30 | ns | h |
| 8 | t _{GLQX} | t _{OLZ} | Output Enable to Output Active | 0 | | 0 | | 0 | | ns | |
| 9 | t _{GHQZ} | t _{HZ} | Output Disable to Output Inactive | | 20 | | 25 | | 30 | ns | h |
| 10 | t _{ELICCH} | t _{PA} | Chip Enable to Power Active | 0 | | 0 | | 0 | | ns | i |
| 11 | t _{EHICCL} | t _{PS} | Chip Enable to Power Standby | | 25 | | 25 | | 25 | ns | b,i |

- Note b: Bringing $\bar{E} \geq V_{IH}$ will not produce standby currents until any non-volatile cycle in progress has timed out. See MODE SELECTION table.
 Note e: \bar{E} , \bar{G} and W must make the transition between V_{IH} (min) to V_{IL} (max), or V_{IL} (max) to V_{IH} (min) in a monotonic fashion.
 Note f: For READ CYCLE 1 and 2, W is high for entire cycle.
 Note g: Device is continuously selected with \bar{E} low, and \bar{G} low.
 Note h: Measured ± 200mV from steady state output voltage. Load capacitance is 5pF.
 Note i: Parameter guaranteed but not tested.

READ CYCLE 1^{f,g}

READ CYCLE 2^f


PRELIMINARY
WRITE CYCLE 1: \overline{W} CONTROLLED^{e,j}
 $(-55^{\circ}\text{C} \leq T_A \leq 125^{\circ}\text{C}) (V_{CC}=5.0\text{V} \pm 10\%)$

| NO. | SYMBOL | | PARAMETER | STK11C68AM-45 | | STK11C68AM-55 | | STK11C68AM-70 | | UNITS | NOTES |
|-----|------------|-----------|----------------------------------|---------------|-----|---------------|-----|---------------|-----|-------|-------|
| | Standard | Alternate | | MIN | MAX | MIN | MAX | MIN | MAX | | |
| 12 | t_{AVAV} | t_{WC} | Write Cycle Time | 45 | | 55 | | 70 | | ns | |
| 13 | t_{WLWH} | t_{WP} | Write Pulse Width | 40 | | 50 | | 65 | | ns | |
| 14 | t_{ELWH} | t_{CW} | Chip Enable to End of Write | 40 | | 50 | | 65 | | ns | |
| 15 | t_{DVWH} | t_{DW} | Data Set-up to End of Write | 15 | | 20 | | 25 | | ns | |
| 16 | t_{WHDX} | t_{DH} | Data Hold After End of Write | 0 | | 0 | | 0 | | ns | |
| 17 | t_{AVWH} | t_{AW} | Address Set-up to End of Write | 40 | | 50 | | 65 | | ns | |
| 18 | t_{AVWL} | t_{AS} | Address Set-up to Start of Write | 0 | | 0 | | 0 | | ns | |
| 19 | t_{WHAX} | t_{WR} | Address Hold After End of Write | 0 | | 0 | | 0 | | ns | |
| 20 | t_{WLOZ} | t_{WZ} | Write Enable to Output Disable | | 25 | | 30 | | 40 | ns | h |
| 21 | t_{WHQX} | t_{OW} | Output Active After End of Write | 5 | | 5 | | 5 | | ns | k |

WRITE CYCLE 1: \overline{W} CONTROLLED^{e,j}

WRITE CYCLE 2: \overline{E} CONTROLLED^{e,j}
 $(-55^{\circ}\text{C} \leq T_A \leq 125^{\circ}\text{C}) (V_{CC}=5.0\text{V} \pm 10\%)$

| NO. | SYMBOL | | PARAMETER | STK11C68AM-45 | | STK11C68AM-55 | | STK11C68AM-70 | | UNITS | NOTES |
|-----|------------|-----------|----------------------------------|---------------|-----|---------------|-----|---------------|-----|-------|-------|
| | Standard | Alternate | | MIN | MAX | MIN | MAX | MIN | MAX | | |
| 22 | t_{AVAV} | t_{WC} | Write Cycle Time | 45 | | 55 | | 70 | | ns | |
| 23 | t_{WLEH} | t_{WP} | Write Pulse Width | 40 | | 50 | | 65 | | ns | |
| 24 | t_{ELEH} | t_{CW} | Chip Enable to End of Write | 40 | | 50 | | 65 | | ns | |
| 25 | t_{DVEH} | t_{DW} | Data Set-up to End of Write | 20 | | 25 | | 35 | | ns | |
| 26 | t_{EHDX} | t_{DH} | Data Hold After End of Write | 0 | | 0 | | 0 | | ns | |
| 27 | t_{AVEH} | t_{AW} | Address Set-up to End of Write | 40 | | 50 | | 65 | | ns | |
| 28 | t_{EHAX} | t_{AS} | Address Hold After End of Write | 0 | | 0 | | 0 | | ns | |
| 29 | t_{AVEL} | t_{WR} | Address Set-up To Start of Write | 0 | | 0 | | 0 | | ns | |
| 30 | t_{WLOZ} | t_{WZ} | Write Enable to Output Disable | | 25 | | 30 | | 40 | ns | h |

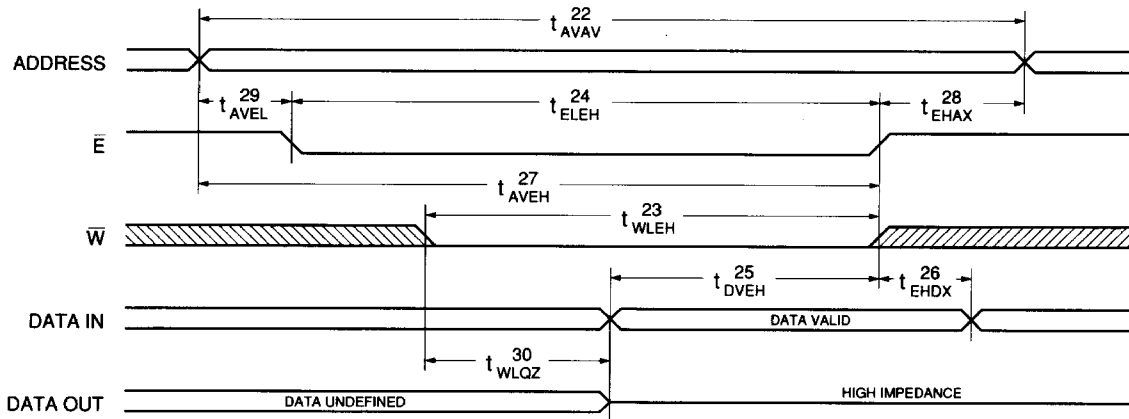
Note e: \overline{E} , \overline{G} and \overline{W} must make the transition between V_{IH} (max) to V_{IL} (max), or V_{IL} (max) to V_{IH} (min) in a monotonic fashion.

Note h: Measured $\pm 200\text{mV}$ from steady state output voltage. Load capacitance is 5pF.

Note j: \overline{E} or \overline{W} must be $\geq V_{IH}$ during address transitions.

Note k: If \overline{W} is low when \overline{E} goes low, the outputs remain in the high impedance state.

WRITE CYCLE 2: \bar{E} CONTROLLED^{h,j}



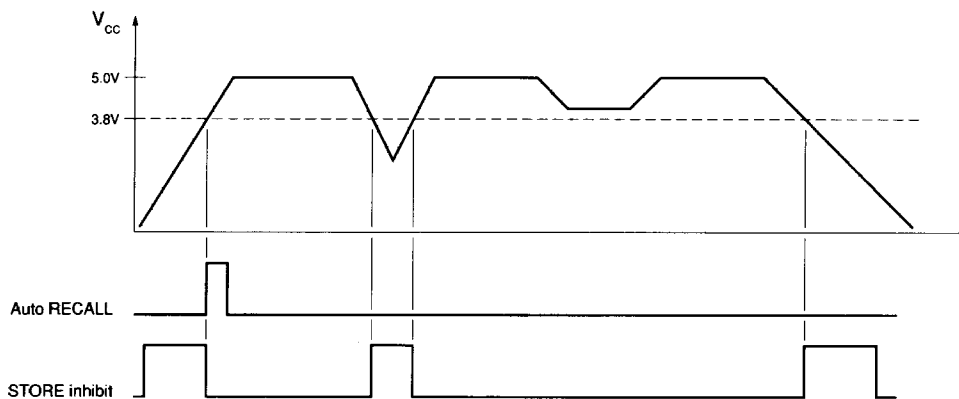
NON-VOLATILE MEMORY OPERATION

MODE SELECTION

| \bar{E} | \bar{W} | $A_{12}-A_0$ (hex) | MODE | I/O | POWER | NOTES |
|-----------|-----------|--------------------|---------------------|---------------|---------|-------|
| H | X | X | Not Selected | Output High Z | Standby | |
| L | H | X | Read RAM | Output Data | Active | n |
| L | L | X | Write RAM | Input Data | Active | |
| L | H | 0000 | Read RAM | Output Data | Active | m, n |
| | | 1555 | Read RAM | Output Data | | m, n |
| | | 0AAA | Read RAM | Output Data | | m, n |
| | | 1FFF | Read RAM | Output Data | | m, n |
| | | 10F0 | Read RAM | Output Data | | m, n |
| | | 0F0F | Non-volatile Store | Output High Z | | m |
| L | H | 0000 | Read RAM | Output Data | Active | m, n |
| | | 1555 | Read RAM | Output Data | | m, n |
| | | 0AAA | Read RAM | Output Data | | m, n |
| | | 1FFF | Read RAM | Output Data | | m, n |
| | | 10F0 | Read RAM | Output Data | | m, n |
| | | 0F0E | Non-volatile Recall | Output High Z | | m |

Note m: The six consecutive addresses must be in order listed – (0000, 1555, 0AAA, 1FFF, 10F0, 0F0F) for a STORE cycle or (0000, 1555, 0AAA, 1FFF, 10F0, 0F0E) for a RECALL cycle. \bar{W} must be high during all six consecutive cycles. See STORE CYCLE and RECALL CYCLE tables and diagrams for further details.
 Note n: I/O state assumes that $\bar{G} \leq V_{IL}$.

AUTOMATIC RECALL AND STORE INHIBIT:

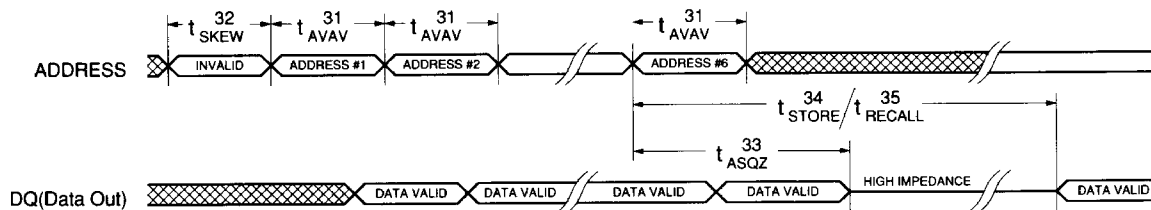
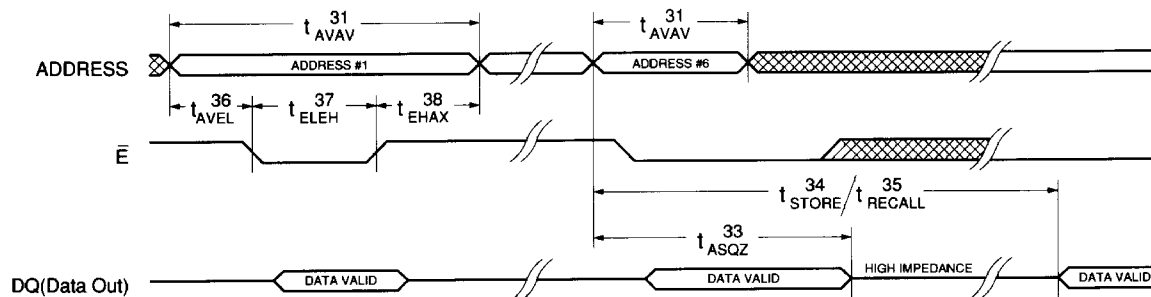


STORE/RECALL CYCLES 1 & 2^{p,u}

 (-55°C ≤ T_A ≤ 125°C) (V_{CC} = 5.0V ± 10%)

| NO. | SYMBOL | | PARAMETER | STK11C68AM-45 | | STK11C68AM-55 | | STK11C68AM-70 | | UNITS | NOTES |
|-----|-------------------|---------------------|---|---------------|-----|---------------|-----|---------------|-----|-------|-------|
| | Standard | Alternate | | MIN | MAX | MIN | MAX | MIN | MAX | | |
| 31 | t _{AVAV} | t _{ACS} | Read Cycle Time | 45 | | 55 | | 70 | | ns | |
| 32 | | t _{SKEW} | Skew Between Sequentially Adjacent Address Pins | | 5 | | 5 | | 5 | ns | o |
| 33 | | t _{ASQZ} | Address Sequence to Output Inactive | | 75 | | 75 | | 75 | ns | q |
| 34 | | t _{STORE} | Store Cycle Time | | 11 | | 11 | | 11 | ms | r |
| 35 | | t _{RECALL} | Recall Cycle Time | | 40 | | 40 | | 40 | μs | r |
| 36 | t _{AVEL} | t _{AE} | Address Set-up to Chip Enable | 0 | | 0 | | 0 | | ns | s |
| 37 | t _{ELEH} | t _{EP} | Chip Enable Pulse Width | 45 | | 55 | | 70 | | ns | s |
| 38 | t _{EHAX} | t _{EA} | Chip Disable to Address Change | 0 | | 0 | | 0 | | ns | s |

- Note o: Skew spec may be avoided by using \bar{E} (STORE/RECALL CYCLE 2).
- Note p: $\bar{W} \geq V_{IH}$ during entire address sequence to initiate a non-volatile cycle. Required address sequences are shown in MODE SELECTION table.
- Note q: Once the software STORE or RECALL cycle is initiated, it completes automatically, ignoring all inputs.
- Note r: Measured with \bar{W} high and \bar{G} and \bar{E} low. Note that STORE cycles are aborted by V_{CC} < 3.8V (STORE Inhibit).
- Note s: \bar{E} must make the transition between V_{IH} (max) to V_{IL} (max), or V_{IL} (max) to V_{IH} (min) in a monotonic fashion.
- Note t: Chip is continuously selected with \bar{E} low.
- Note u: Addresses #1 through #6 are found in the MODE SELECTION table. Address #6 determines whether the STK11C68AM performs a STORE or RECALL. A RECALL cycle is performed automatically at power up when V_{CC} exceeds 3.8V.

STORE/RECALL CYCLE 1^{p,t}

STORE/RECALL CYCLE 2^p


DEVICE OPERATION

The STK11C68AM has two separate modes of operation: SRAM mode and non-volatile mode. In SRAM mode the memory operates as an ordinary static RAM. In non-volatile operation, data is transferred from SRAM to EEPROM or from EEPROM to SRAM. In this mode SRAM functions are disabled.

SRAM READ

The STK11C68AM performs a read cycle whenever \bar{E} and \bar{G} are LOW and \bar{W} is HIGH. The address specified by the 13 addresses, A_{0-12} specify which of the 8192 data bytes will be accessed. If the read cycle is initiated by an address transition, the outputs will be valid at t_{AVQV} (READ CYCLE 1). If the cycle is initiated by a clock signal the outputs will be valid at t_{ELQV} or at t_{GLQV} , whichever is later (READ CYCLE 2). As long as the clocks remain in the READ state the outputs will repeatedly respond to address changes within t_{AVQV} access time without the need for additional clocking cycles. The outputs remain valid until another address change or until \bar{E} or \bar{G} is brought HIGH or \bar{W} is brought LOW.

SRAM WRITE

A write cycle is performed whenever \bar{E} and \bar{W} are LOW. The address inputs must be stable prior to entering the WRITE cycle and must remain stable until either \bar{E} or \bar{W} go HIGH at the end of the cycle. The data on the eight inputs, DQ_{0-7} , will be written into the memory location specified by the address inputs. The DQ data may be changed during the write cycle. Valid data must, however, be present t_{DVWH} before the end of a \bar{W} controlled WRITE or t_{DVEH} before the end of an \bar{E} controlled WRITE for the memory cells to be fully written.

It is recommended that \bar{G} be kept HIGH during the entire WRITE cycle to avoid data bus contention on the common I/O's. If \bar{G} is left LOW however, internal circuitry will turn off the output buffers t_{WHQZ} after \bar{W} goes LOW. Until that time, data bus contention is possible.

NON-VOLATILE STORE

The STK11C68AM STORE cycle is initiated by executing sequential READ cycles from six specific address locations. By relying on READ cycles only, the STK11C68AM implements non-volatile operation while remaining pin-for-pin compatible with standard 8Kx8 SRAM's. During the STORE cycle, an erase of the previous non-volatile data is first performed, followed by a program of the non-volatile elements. The program operation copies the SRAM data into non-volatile storage. Once a STORE cycle is initiated, further input and output are disabled until the cycle is completed.

Because a sequence of addresses is used for STORE ini-

tiation, it is critical that no invalid address states intervene in the sequence or the sequence will be aborted. The maximum skew between address inputs A_{0-12} for each address state is t_{SKEW} (STORE CYCLE 1). If t_{SKEW} is exceeded it is possible that the transitional data state will be interpreted as a valid address and the sequence will be aborted. If \bar{E} controlled READ cycles are used for the sequence (STORE CYCLE 2), address skew is no longer a concern.

To enable the STORE cycle the following READ sequence must be performed:

| | | | |
|----|--------------|------------|----------------------|
| 1. | Read address | 0000 (hex) | Valid READ |
| 2. | Read address | 1555 (hex) | Valid READ |
| 3. | Read address | 0AAA (hex) | Valid READ |
| 4. | Read address | 1FFF (hex) | Valid READ |
| 5. | Read address | 10F0 (hex) | Valid READ |
| 6. | Read address | 0F0F (hex) | Initiate STORE Cycle |

Once the sixth address in the sequence has been entered, the STORE cycle will commence and the chip will be disabled. It is important that READ cycles and not WRITE cycles be used in the sequence, although it is not necessary that \bar{G} be LOW for the sequence to be valid. After the t_{ASQV} cycle time has been fulfilled, the SRAM will again be activated for READ and WRITE operation.

HARDWARE PROTECT

The STK11C68AM offers hardware protection against inadvertent STORE cycles through V_{CC} Sense. A STORE cycle will not be initiated, and one in progress will discontinue, if V_{CC} goes below 3.8V.

NON-VOLATILE RECALL

A RECALL of the EEPROM data into the SRAM is initiated with a sequence of READ operations in a manner similar to the STORE initiation. To initiate the RECALL cycle the following sequence of READ operations must be performed:

| | | | |
|----|--------------|------------|-----------------------|
| 1. | Read address | 0000 (hex) | Valid READ |
| 2. | Read address | 1555 (hex) | Valid READ |
| 3. | Read address | 0AAA (hex) | Valid READ |
| 4. | Read address | 1FFF (hex) | Valid READ |
| 5. | Read address | 10F0 (hex) | Valid READ |
| 6. | Read address | 0F0E (hex) | Initiate RECALL Cycle |

Internally, RECALL is a two step procedure. First, the SRAM data is cleared and second, the non-volatile information is transferred into the SRAM cells. The RECALL operation in no way alters the data in the EEPROM cells. The non-volatile data can be recalled an unlimited number of times.

On power-up, once V_{CC} exceeds the V_{CC} sense voltage of 3.8V, a RECALL cycle is automatically initiated. For this reason, SRAM operation cannot commence until t_{RECALL} after V_{CC} is high.

